

# Si4411DY

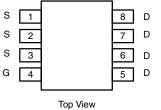
New Product

## Vishay Siliconix

# P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
- 30	0.010 at V <sub>GS</sub> = - 10 V	- 13			
	0.0155 at V <sub>GS</sub> = - 4.5 V	- 10			





Si4411DY-T1-E3 (Lead (Pb)-free)

### **FEATURES**

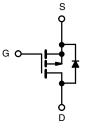
• TrenchFET<sup>®</sup> Power MOSFET

#### **APPLICATIONS**

- Notebook
  - Load Switch
  - Battery Switch



Ordering Information: Si4411DY-T1



P-Channel MOSFET

Parameter		ss otherwise r	10 secs	Steady State	Unit
		Symbol		Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 30		V
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Drain Current (T 150 °C)	T <sub>A</sub> = 25 °C	– I <sub>D</sub>	- 13	- 9	А
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		- 10.5	- 7.5	
Pulsed Drain Current		I <sub>DM</sub>	- 50		А
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 2.7	- 1.36	
Marian Dissisting	T <sub>A</sub> = 25 °C	Pn	3.0	1.5	W
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	١D	1.9	0.95	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	- R <sub>thJA</sub>	33	42	
Maximum Junction-to-Ambient*	Steady State		70	85	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	16	21	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

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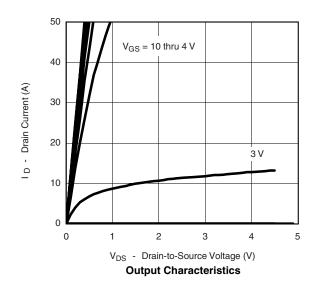


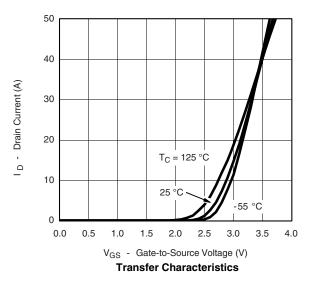
<b>SPECIFICATIONS</b> $T_J = 25 \text{ °C}$ , unless otherwise noted								
Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit		
Static								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \ \mu A$	- 1.0		3.0	V		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1			
		$V_{DS}$ = - 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C			- 10	- μΑ		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 V, V_{GS} = -10 V$	- 30			А		
Drain-Source On-State Resistance <sup>a</sup>	r	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 13 A		0.008	0.010	0		
	r <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 10 A		0.0125	0.0155	Ω		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 13 A		40		S		
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = - 2.7 A, V <sub>GS</sub> = 0 V		- 0.74	- 1.1	V		
Dynamic <sup>b</sup>								
Total Gate Charge	Qg			43	65			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = - 15 V, $V_{GS}$ = - 5 V, $I_{D}$ = - 13 A		8.5		nC		
Gate-Drain Charge	Q <sub>gd</sub>			18.5				
Gate Resistance	Rg			3.4		Ω		
Turn-On Delay Time	t <sub>d(on)</sub>			18	30			
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$		15	25			
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_{\text{D}}\cong$ - 1 A, $\text{V}_{\text{GEN}}$ = - 10 V, $\text{R}_{\text{G}}$ = 6 $\Omega$		140	250	ns		
Fall Time	t <sub>f</sub>			75	120			
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 2.1 A, di/dt = 100 A/μs		60	100			

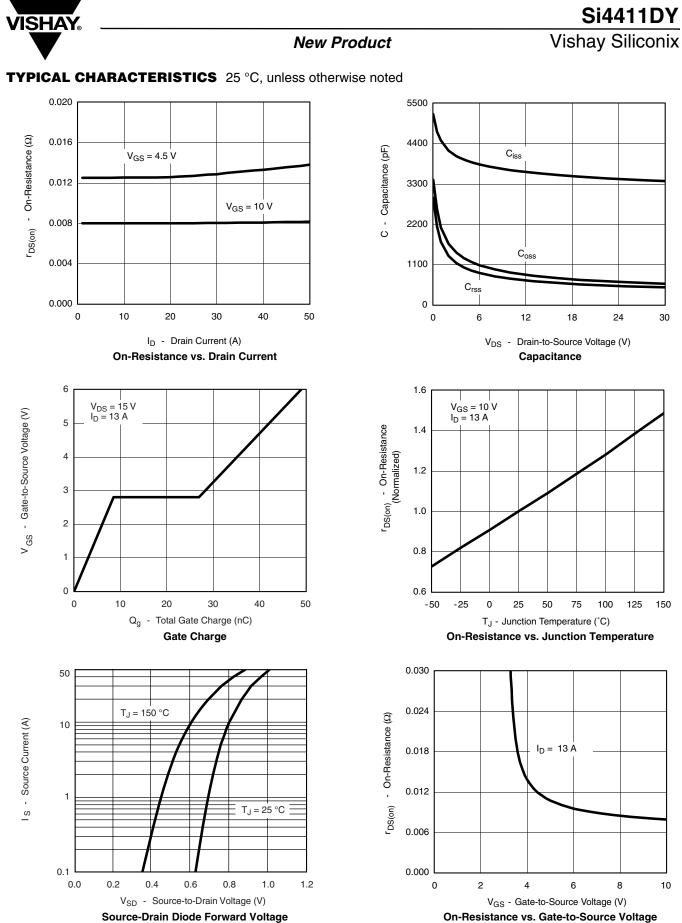
Notes a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





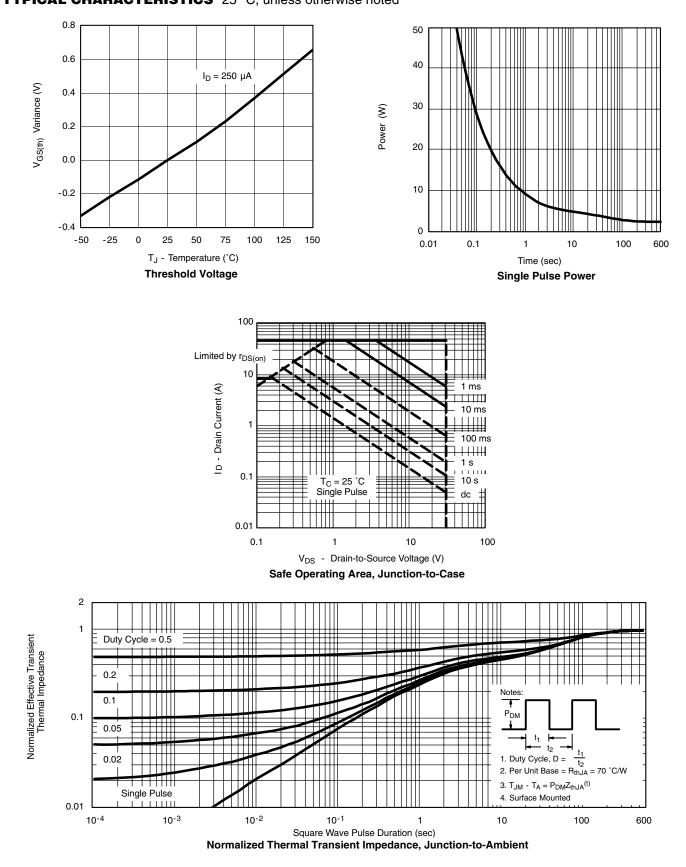


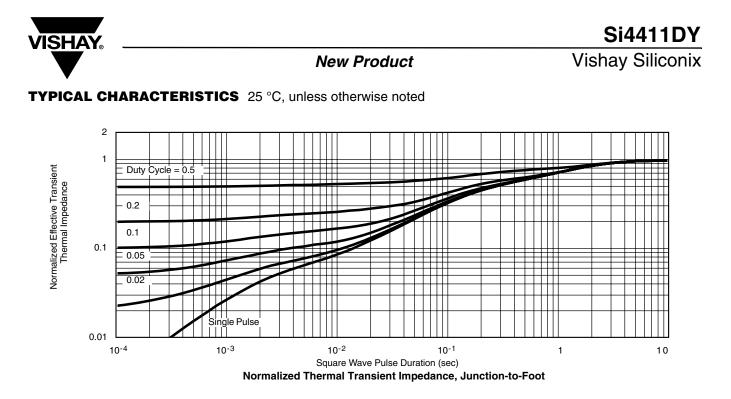
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**New Product** 



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